

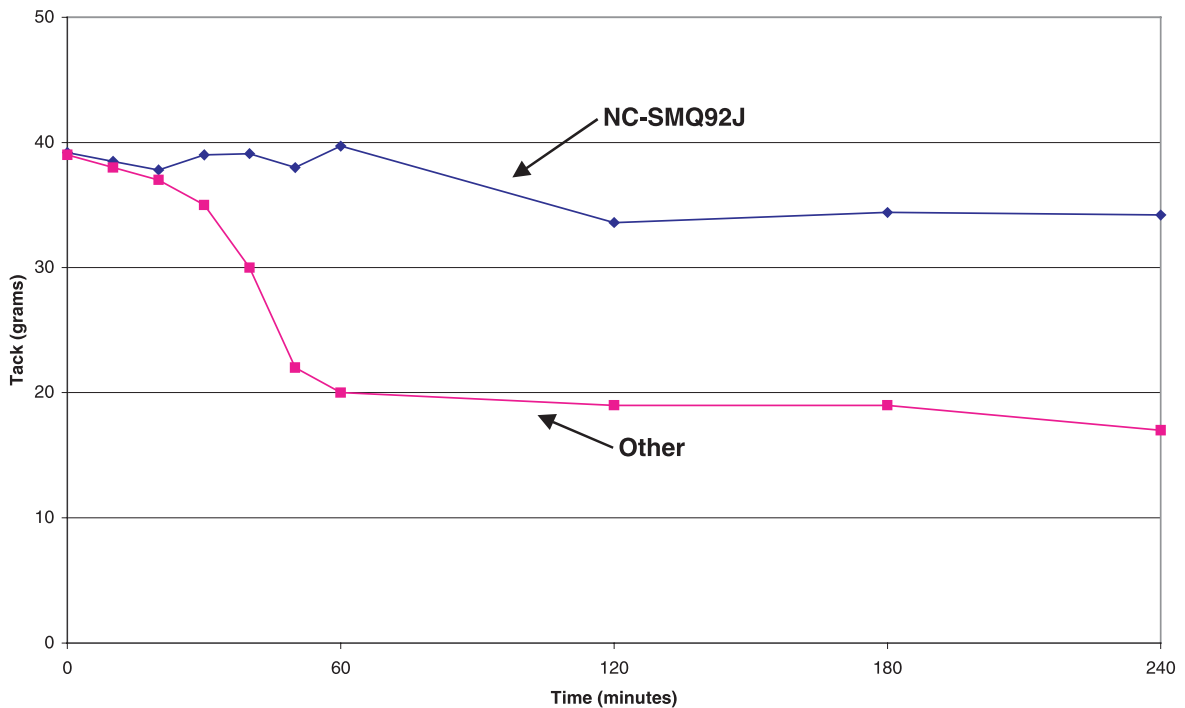
# TACK vs. TIME (stressed conditions)

## NC-SMQ<sup>®</sup>92J Solder Paste



The following test was designed to simulate the true life of a solder paste on a stencil. Indium Corporation's Research & Development Facility tested NC-SMQ92J's tack stability over time while the paste was continuously being stressed (ICA's proprietary method for stressing the paste was developed to simulate the shear caused by a squeegee blade). Tack measurements were taken at ten-minute intervals for the first seven readings and every sixty minutes thereafter on a Malcom TK-1 Tackiness Tester per IPC-TM-650. The tack strength and stability on the NC-SMQ92J was maintained through out the length of the study.

**NC-SMQ92J Tack vs. Time (Under Stress)**



Results demonstrate NC-SMQ92J's ability to maintain tack strength over a four-hour period of continuous shearing.